



## Heat Sink Compound

Detailed product specifications are available on: [us.100y.com.tw](http://us.100y.com.tw)



### DESCRIPTION

- Color: white
- Viscosity: 300 poise
- Density: over 2.0 @ 20°C
- Thermal conductivity: 4.18W/MK
- Temperature usage: 0°C to 170°C
- Storage temperature: under 25°C
- Material: Dow corning340

### INTRODUCTION

Apply this thermal transfer compound between the CPU, or the video card and the heat sink to aid in the transfer of heat from the former to the latter. These grease are not electrically conductive or capacitive and it doesn't even need a burn-in period

Part No.	Product No.	Manufacturer	Description	Capacity
17842	OTR-HTK-002	COOLER MASTER	Heatsink Compound	2g



### DESCRIPTION

- Color: gray
- Viscosity: 1700 poise
- Density: over 2.0 @ 20°C
- Thermal conductivity: 6.8W/MK
- Temperature usage: -50°C to 170°C
- Storage temperature: under 10°C
- Material: shin Etsu 7762

### INTRODUCTION

Apply this thermal transfer compound between the CPU, or the video card and the heat sink to aid in the transfer of heat from the former to the latter. These grease are not electrically conductive or capacitive and it doesn't even need a burn-in period

Part No.	Product No.	Manufacturer	Description	Capacity
17843	OTR-PTK-002	COOLER MASTER	Heatsink Compound	1.6g



### PHYSICAL PROPERTIES

- Color: white
- Appearance: opaque, creamy paste
- Specific Gravity: 2.3

- Bleed-7 days at room temperature: 0.4%  
24 hours at 150°C: 0.5%
- Evaporation-7days at room temperature: 0.02%  
24hours at 200°C: 0.2%
- Volume resistivity, at room temperature: 1.5\*10<sup>14</sup> ohm.com
- Thermal conductivity: 2\*10<sup>-3</sup> cal/cm. sec. °C

Part No.	Product No.	Description	Capacity
10579	U1000	Heatsink Compound	1kg/Bottle

## Silicone & Mica Insulator

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### TYPICAL APPLICATIONS INCLUDE

- Mount heat sink onto BGA graphic processor or drive processor
- Mount heat spreader onto power converter PCB or onto motor control PCB

### FEATURES AND BENEFITS

- Thermal impedance 0.86oC-in 2/W (@100psi)
- High bond strength to a variety of surfaces
- Double sided pressure sensitive adhesive tape
- High performance, thermally conductive acrylic adhesive
- Can be used instead of heat cure adhesive, screw nounting or clip mounting

Part No.	Product No.	Manufacturer	Description	L*W*Thickness(mm)	Color	c/w	w/m-k	KV-AC	Material	Adhesive
16870	Bond Ply100-182*255*0.2mm	BERGQUIST	Bergquist_8mil Silicone Insulator	182*255*0.2mm	White	0.86	0.8		Fiberglass	Adhesive
16864	Bond Ply108-28*28*0.2mm	BERGQUIST	Bergquist_8mil Silicone Insulator	28*28*0.2mm	White					Adhesive
16865	Bond Ply108-40*40*0.2mm	BERGQUIST	Bergquist_8mil Silicone Insulator	40*40*0.2mm	White					Adhesive
16866	Bond Ply108-44*44*0.2mm	BERGQUIST	Bergquist_8mil Silicone Insulator	44*44*0.2mm	White					Adhesive
16867	Bond Ply108-49*49*0.2mm	BERGQUIST	Bergquist_8mil Silicone Insulator	49*49*0.2mm	White					Adhesive
16873	CPU PAD-9mil-201*255*0.23mm	BERGQUIST	Bergquist_Silicone Insulator	201*255*0.23mm	Tan	4.2	0.4			Adhesive
16871	SP900S-230*360*0.23mm	BERGQUIST	Bergquist_9mil Silicone Insulator	230*360*0.23mm	Mauve	0.2	1.6	5.5/8.3	Sil-Pad	Adhesive
16868	SP900SA-28*28*0.23mm	BERGQUIST	Bergquist_Silicone Insulator	28*28*0.23mm	Mauve	0.2	1.6	5.5/8.3	Sil-Pad	Adhesive
16869	SP900SA-40*40*0.23mm	BERGQUIST	Bergquist_Silicone Insulator	40*40*0.23mm	Mauve	0.2	1.6	5.5/8.3	Sil-Pad	Adhesive
16872	Sil Pad800S-211*305*0.23mm	BERGQUIST	Bergquist_5mil Silicone Insulator	211*305*0.23mm	Gold	0.1	1.6	1.7/3.0		Adhesive



- Between a chassis wall and other surface
- Areas where heat needs to be transferred to the
- Frame or other type of heat spreader
- Between a CPU and a heat spreader
- Between a semiconductor and heat sink
- Replacement for messy grease

Part No.	Product No.	Description	L*W*Thickness(mm)	Adhesive
12877	GPD125-200*400*3mm	GAP PAD	200*400*3mm	Adhesive
12878	GPD160-200*400*3mm	GAP PAD	200*400*3mm	Adhesive



### APPLICATIONS

- Between chasis wall and other surface
- CDROM Cooling
- Area where heat needs to be transferred to a frame chassis, or other type of heat spreader
- Between CPU and heat spreader
- Between a semiconctor and heat sink

Part No.	Product No.	Description	L*W*Thickness(mm)	Color	c/w	w/m-k	KV-AC	Material
33577	GPS160	Gap Pad Vo Soft Silicone Insulator	200*400*4.0 mm	pink	5	0.8	>6	Low modulus silicone polymer
17647	Gap Pad Vo Soft-200*400*3 mm	Gap Pad Vo Soft Silicone Insulator	200*400*3 mm(0.118inch)	pink	5	0.8	>6	Low modulus silicone polymer

